

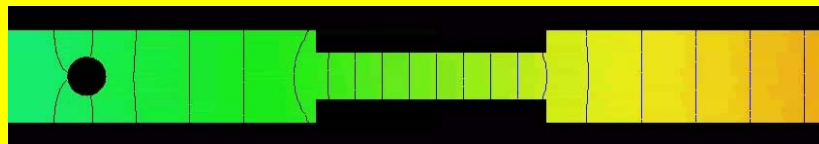
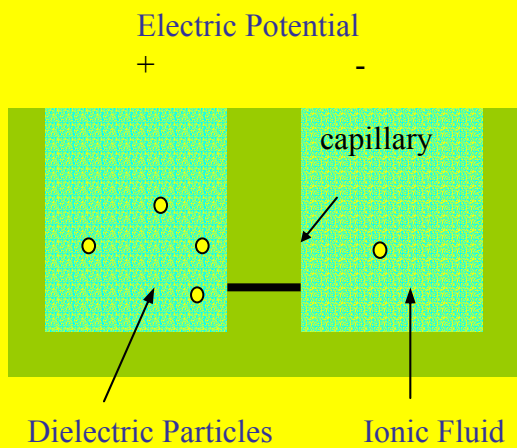
APPLICATIONS OF COULTER COUNTER BASED SENSORS



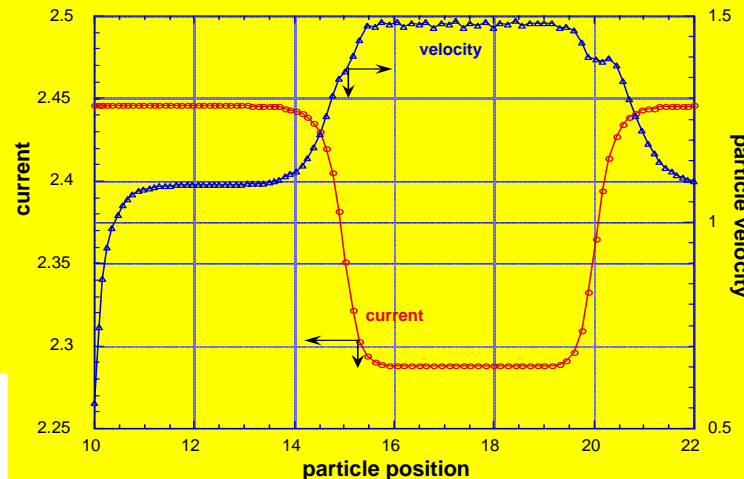
- by Mpitulo Kala-Lufulwabo
- Michael Riegelman (mentor)
- Dr. Haim H. Bau (advisor)

Applications and Principles

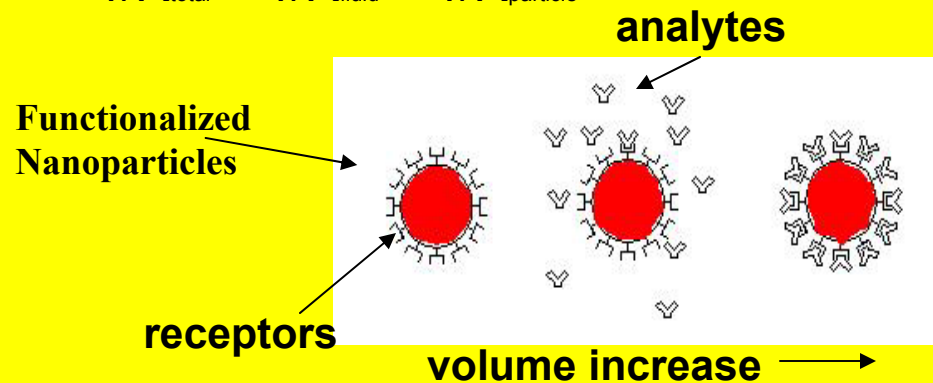
What Exactly is a Coulter Counter?



$$1/R_{\text{total}} = 1/R_{\text{fluid}} + 1/R_{\text{particle}}$$

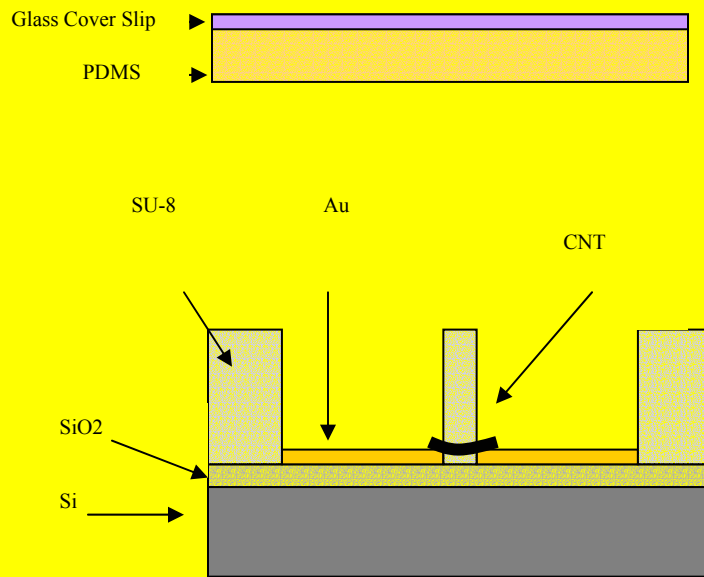


- This device can be used as a chemical or biosensor to detect the binding of target analyte to functionalized nanoparticles

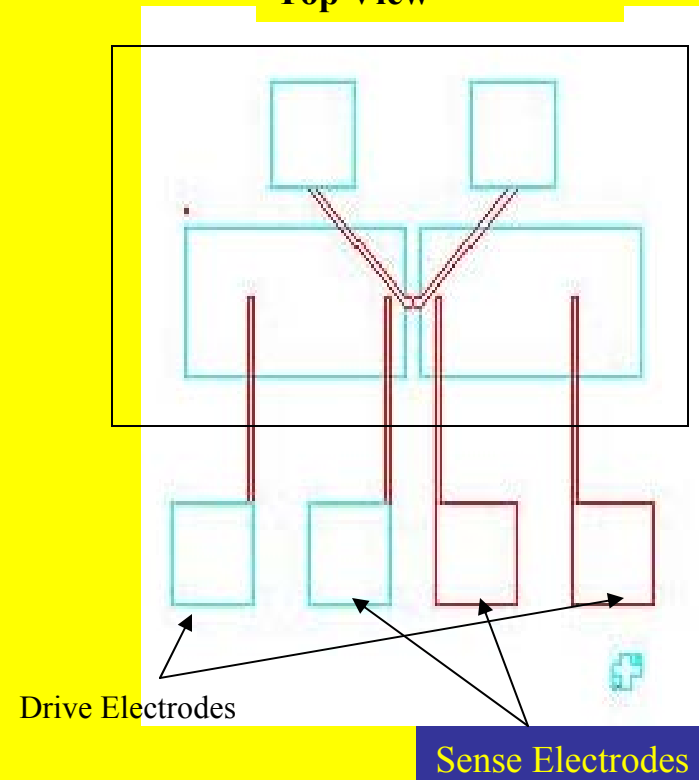


Device Design

Side View



Top View



MICROFABRICATION

Knowledge, Hands on Experience, Skills:

Photolithography

Polymer Processing

Electron Beam Evaporator

Electroplating

Bulk/Surface Micromachining (etching)

Chemical Vapor Deposition (CVD)

Oxidation and Doping Processes

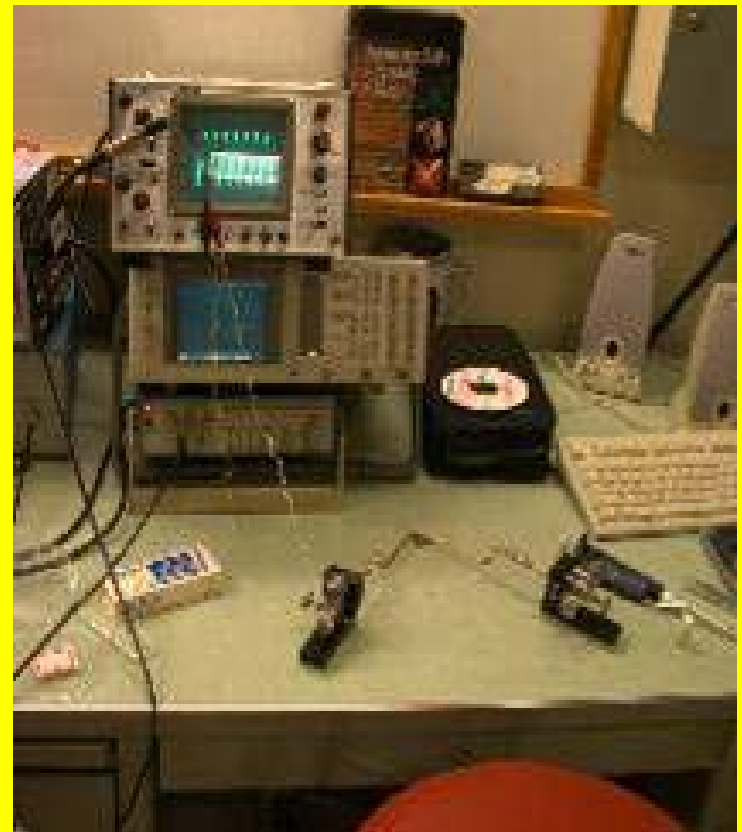
Magnetron sputtering

Probe Station →

Optical Microscope

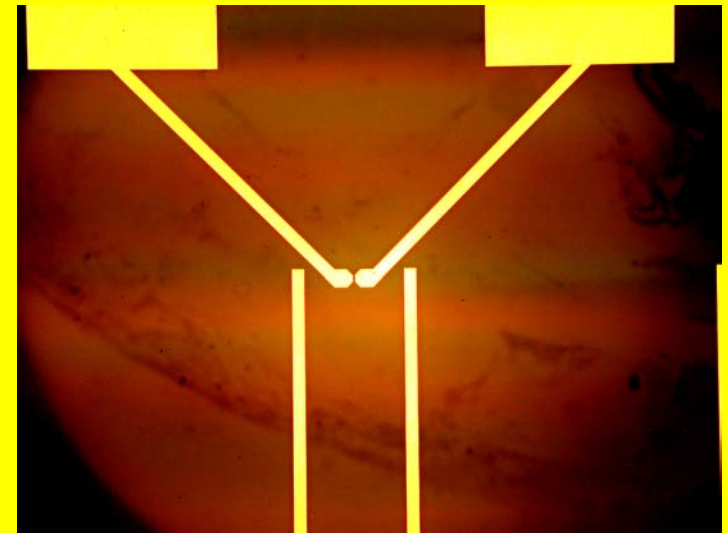
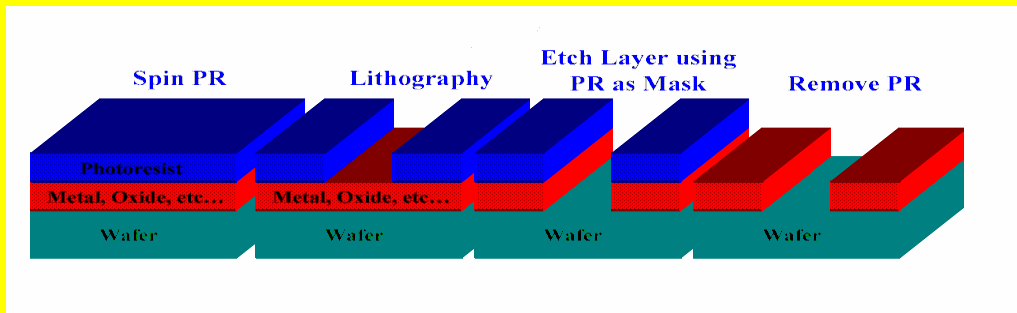
Scanning Electron Microscope (SEM)

Ultrasonic Transduction



Nanofabrication Procedure

- 1) On p-type <100> silicon wafer, perform basic cleaning
- 2) Grow 1 micron of thermal oxide for electrical insulation
- 3) E-beam evaporate gold onto wafers
- 4) Pattern gold electrodes through the liftoff/wet etching process
 - Spin on positive/negative photoresist
 - Expose wafer with mask 1
- 5) Strip resist and electrodes will be patterned

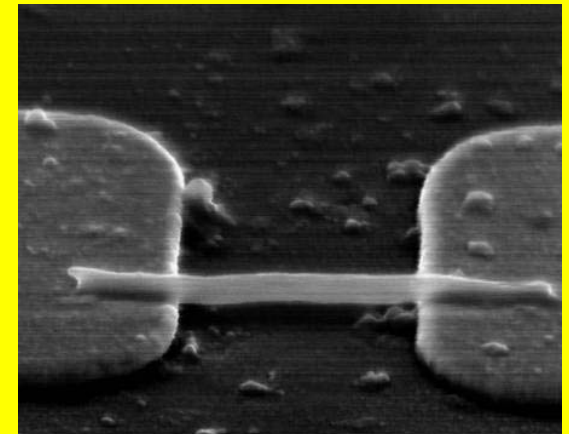
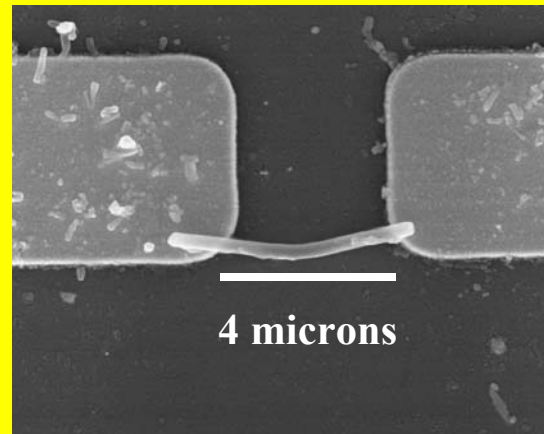
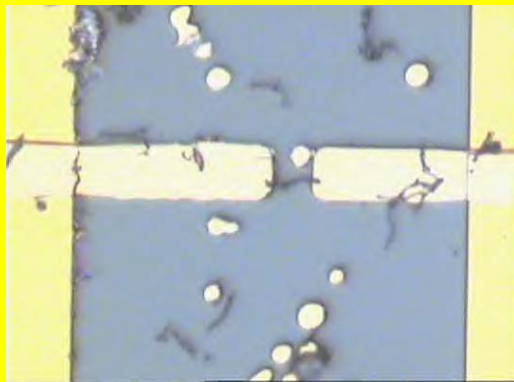
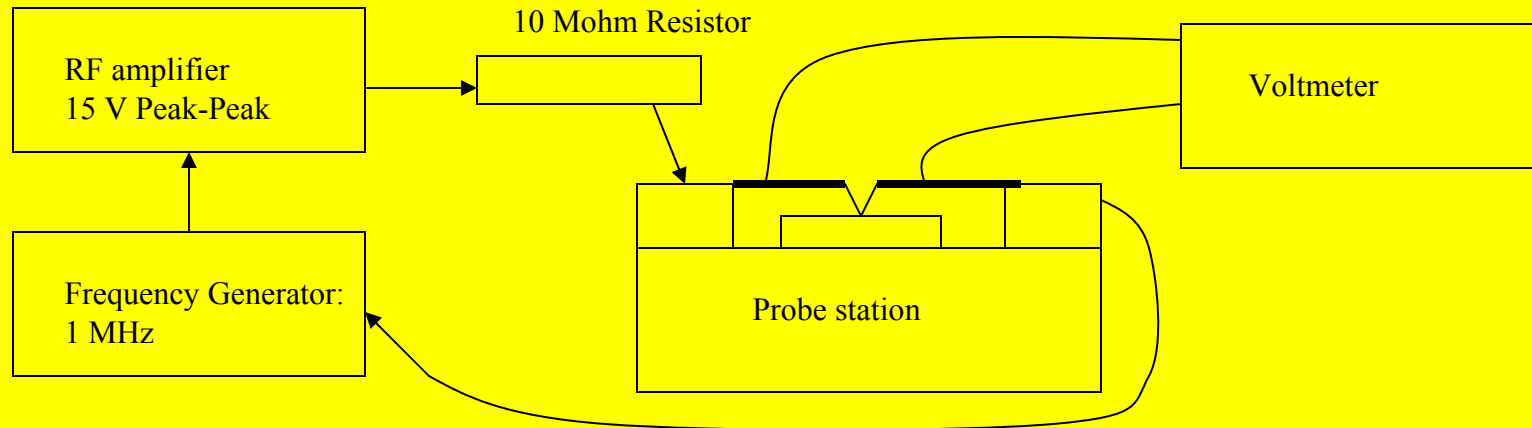


Electrodes on SiO₂ at 2x magnification

Dielectrophoretic Trapping Procedure

6) Trap CNT between gold electrodes using a dielectrophoretic trapping approach

Experimental Setup and Initial Results



Multi-walled CNT Trapped Between Electrodes

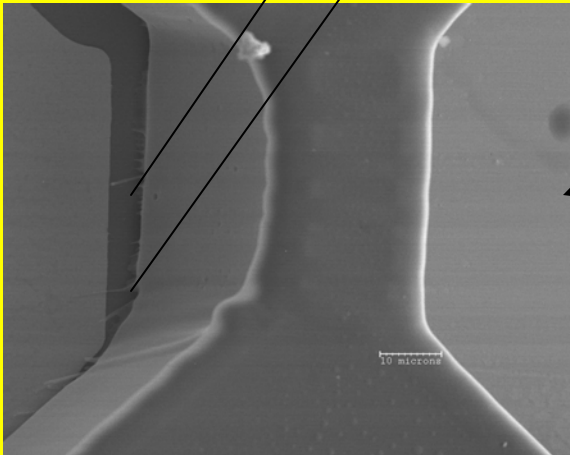
SU-8 Interface

7) Pattern SU-8 Reservoirs Around Tube Ends

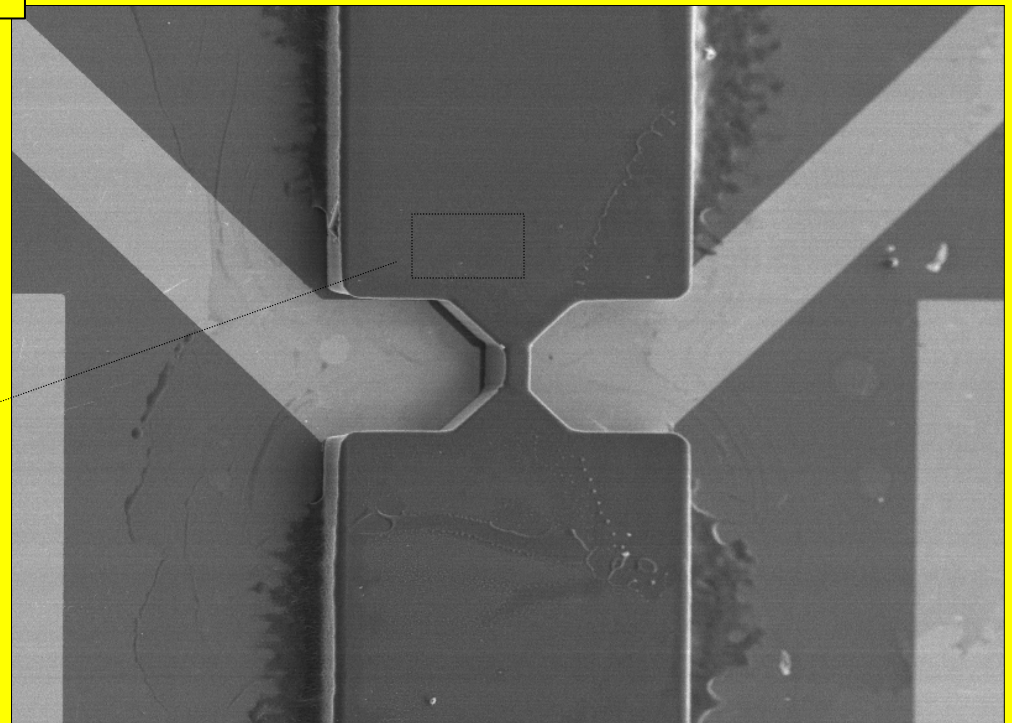
Use of Scanning Electron Microscope (SEM) to Visualize SU-8 interface and carbon nanotube

Gold electrode

Carbon nanotubes



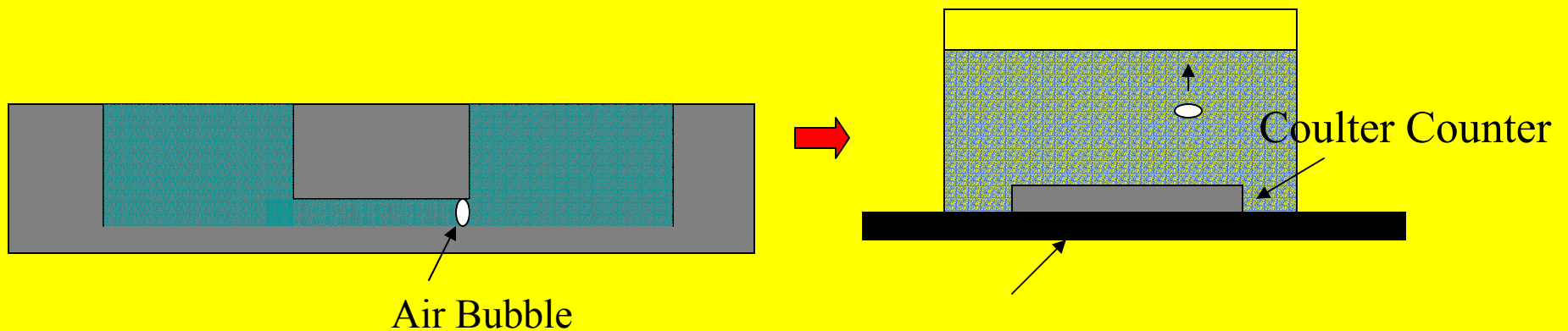
Trapped CNT under SU-8 wall



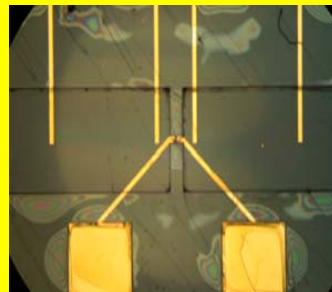
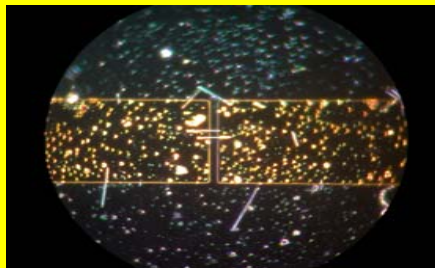
SU-8 Reservoirs formed around the tube ends

Issues and Hopeful Solutions

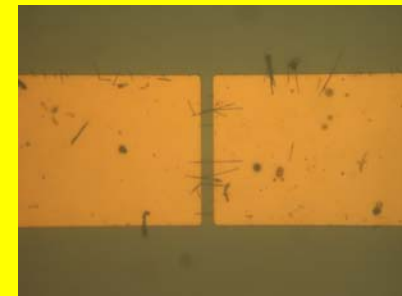
1) Assumed Problem filling the tubes



2) Adhesion Between SU-8 and Substrate



Etch away oxide layer with HF



3) Surface Tension Issues



Surfactant - detergent

Other Issues

- “Over” Etching and Undercutting of Au electrodes: Isotropic Wet Etching vs. Liftoff
- Optimization of SU-8 Processing: Modification of exposure and baking time
- CNT Trapping: concentration of tubes, voltage and frequency modifications for different chips
- Electrical measurements of CNTs before and after trapping and in attempt to sense tube filling

If the Future is Not Now, How Soon is it?

- Groundwork is set for the creation of a functional microfabricated device in the near future
- Develop better optical and electrical sensing techniques
- Down the Road:** Minimizing Coulter Counter to create breakthroughs in biosensor and chemical applications

THANK YOU!!!!!!